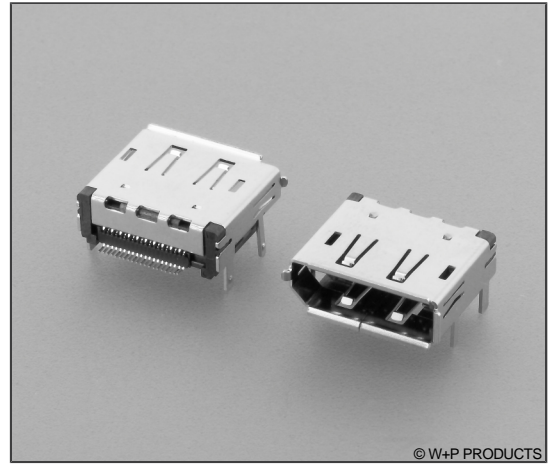
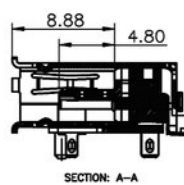
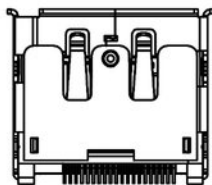
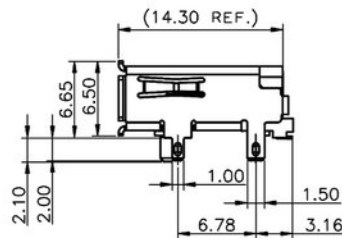
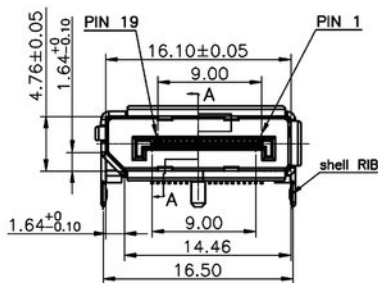
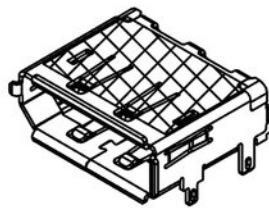
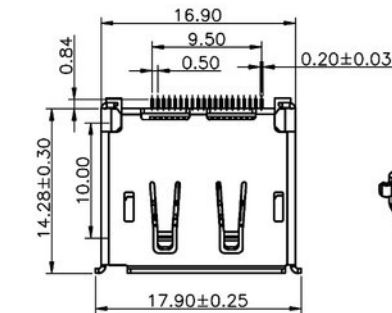


Technische Daten / Technical Data

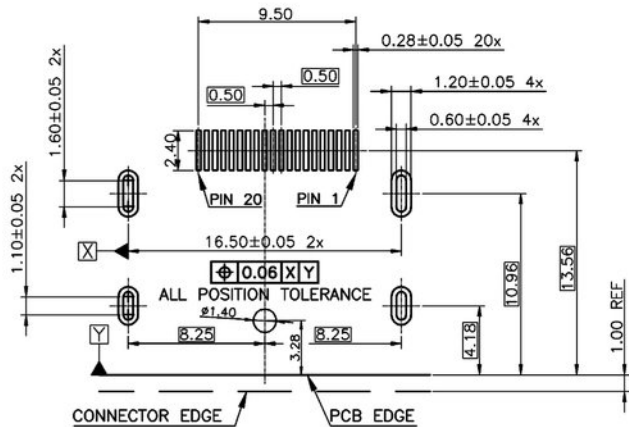
Isolierkörper <i>Insulator</i>	Thermoplastischer Kunststoff, nach UL94 V-0 <i>Thermoplastic, rated UL94 V-0</i>
Farbe <i>Colour</i>	Schwarz <i>Black</i>
Kontaktmaterial <i>Contact Material</i>	Kupferlegierung <i>Copper alloy</i>
Kontaktoberfläche <i>Contact Surface</i>	Im Steckbereich vergoldet / Lötseite verzinkt <i>Gold plated mating area / tin plated solder area</i>
Durchgangswiderstand <i>Contact Resistance</i>	< 30 mΩ
Isolationswiderstand <i>Insulation Resistance</i>	> 100 MΩ
Spannungsfestigkeit <i>Test Voltage</i>	500 V _{AC}
Nennspannung <i>Voltage Rating</i>	40 V _{AC/RMS}
Nennstrom <i>Current Rating</i>	500 mA
Temperaturbereich <i>Temperature Range</i>	-25°C ... +85°C
Verarbeitung <i>Processing</i>	Reflow-Lötverfahren <i>Reflow soldering</i>



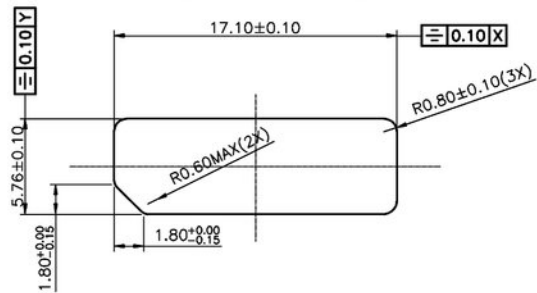
© W+P PRODUCTS



SECTION: A-A



RECOMMENDED P.C.B. LAYOUT (THICKNESS=1.60mm)
TOLERANCE UNSPECIFIED ±0.05mm



REFERENCE PANEL CUT OUT DIMENSIONS

Series	Entry Type	Connector Type	Locating Pegs	Plating*	Package*
8470	2	2	1	80	FTR
	2 Buchse Female	2 Liegend Horizontal	1 mit Pos.hilfe, ohne Rippen with loc. peg, w/o ribs	80 sel. Au 0,75µm / Sn 60 sel. Au flash / Sn	FTR (Option) Tape & Reel Tape & Reel

* Dies ist ein **Bestellbeispiel** -
bitte durch Ihre Spezifikationen ersetzen.
* This is an **order example** -
please replace by your specifications.

Informationen zum Reflow-Lötverfahren

Reflow Soldering Information

Reflow-Lötempfehlung

Reflow Soldering Recommendation

Die Bauteile sollten gemäß folgendem Temperatur-Profil in Anlehnung an die IPC/JEDEC J-STD-020C für bleifreies Löten im Reflow-Verfahren verarbeitet werden (Maximalwerte).

Profileigenschaft	Kennwert
Temperatur Minimum T_{Smin}	150°C
Temperatur Maximum T_{Smax}	200°C
Dauer $T_{Smin} - T_{Smax}$	60-180s
Temperatur Lötbereich T_L	217°C
Verweildauer oberhalb T_L	60-180s
Ramp-Up Rate $T_{Smax} - T_P$	max. 3°C / s
Höchsttemperatur T_P	260°C ±5
Dauer Höchsttemperatur	20-40s
Ramp-Down Rate $T_{Pmax} - T_{Smin}$	6°C / s
Dauer 25°C - Höchsttemperatur T_P	Max. 8 min

Items should be soldered according to IPC/JEDEC J-STD-020C temperature profile for leadfree reflow soldering (maximum values).

Profile Feature	Key Values
Minimum Temperature T_{Smin}	150°C
Maximum Temperatur T_{Smax}	200°C
Duration $T_{Smin} - T_{Smax}$	60-180s
Soldering Range Temperature T_L	217°C
Duration above T_L	60-180s
Ramp-Up Rate $T_{Smax} - T_P$	max. 3°C / s
Peak Temperature T_P	260°C ±5
Duration Peak Temperature	20-40s
Ramp-Down Rate $T_{Pmax} - T_{Smin}$	6°C / s
Duration 25°C - Peak Temp. T_P	Max. 8min

